

# Specification of Thermoelectric Module

## TEC1-12710

### Description

The 127 couples, 40mm × 40mm size single module is made of our high performance ingots to achieve superior cooling performance up to 70°C or larger delta Tmax. Designed for superior cooling and heating applications. We can design and manufacture custom made module according to your requirements. Please contact us. Minimums do apply.

### Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

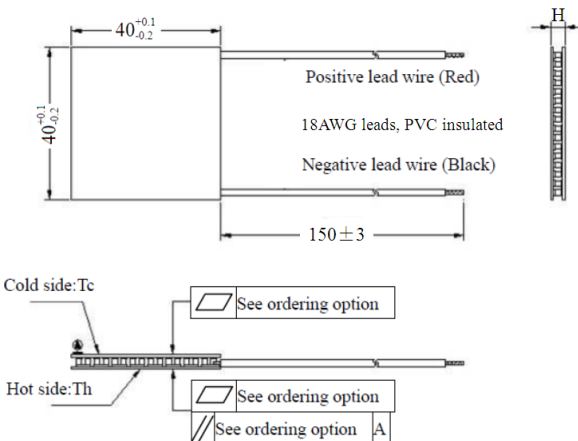
### Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

### Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>
DT <sub>max</sub> (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U <sub>max</sub> (Voltage)	16	17.2	Voltage applied to the module at DT <sub>max</sub>
I <sub>max</sub> (Amps)	10.1	10.1	DC current through the modules at DT <sub>max</sub>
Q <sub>Cmax</sub> (Watts)	101.1	110.5	Cooling capacity at cold side of the module under DT=0 °C
AC resistance (Ohms)	1.15~1.35	1.27~1.49	The module resistance is tested under AC

### Geometric Characteristics Dimensions in millimeters



### Manufacturing Options

#### A. Solder:

1. T100: BiSn (Melting Point=138°C)
2. T200: CuSn (Melting Point= 227 °C)

#### B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant
4. Customer specify sealing

#### C. Ceramics:

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)(AlO)
2. Aluminum Nitride (AlN)

#### D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized (Copper-Nickel plating)

### Flatness/ Parallelism Option

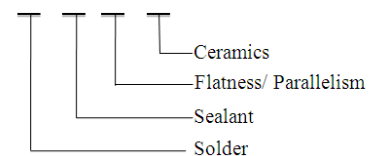
Suffix	Thickness H / (mm)	Flatness/ Parallelism (mm)	Lead wire length (mm) Standard/Optional length
TF	0:3.6±0.15	0:0.05/0.05	150±3/Specify
TF	1:3.6±0.10	1:0.025/0.025	150±3/Specify
TF	2:3.6±0.05	2:0.015/0.015	150±3/Specify

Eg. TF01: Thickness 3.6±0.15(mm) and Flatness 0.025/0.025(mm)

If you need higher strict tolerance on thickness and flatness, please specify, we can cater for.

### Naming for the Module

TEC1- 12710- X - X - X - X



TEC1- 12710- T100 -NS - TF02 - AlO

T100: Solder, BiSn (Melting Point=138 °C)

NS: No sealing

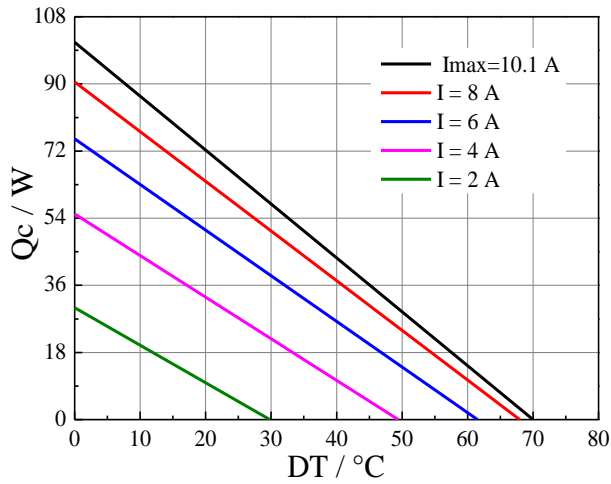
AlO: Alumina white 96%

TF02: Thickness ±0.15(mm) and Flatness/Parallelism 0.015/0.015(mm)

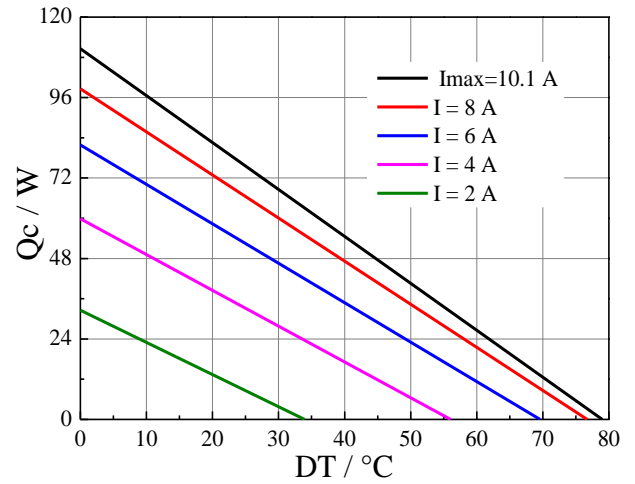
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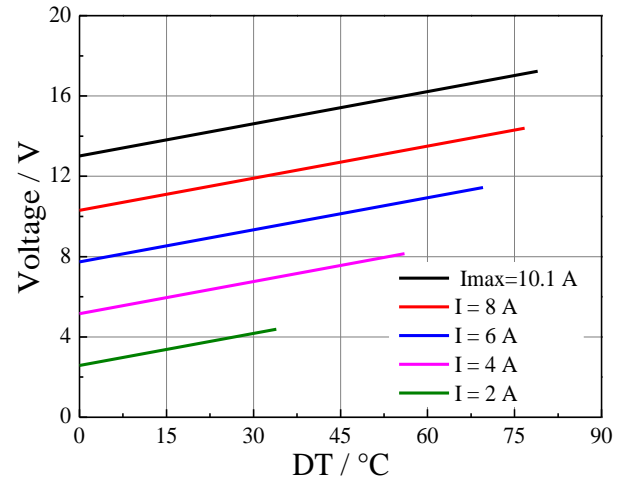
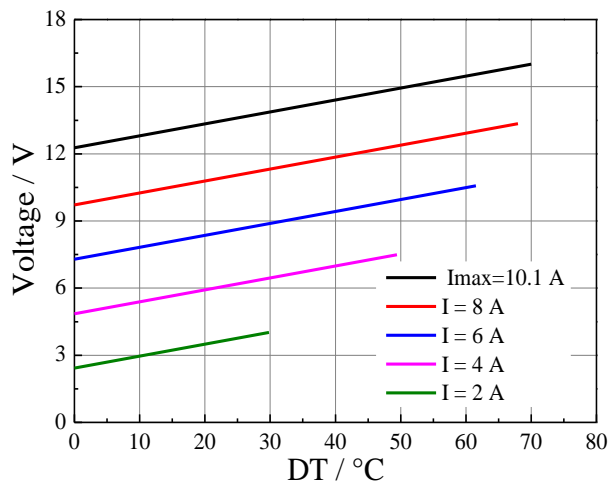
### Performance Curves at $T_h=27\text{ }^\circ\text{C}$



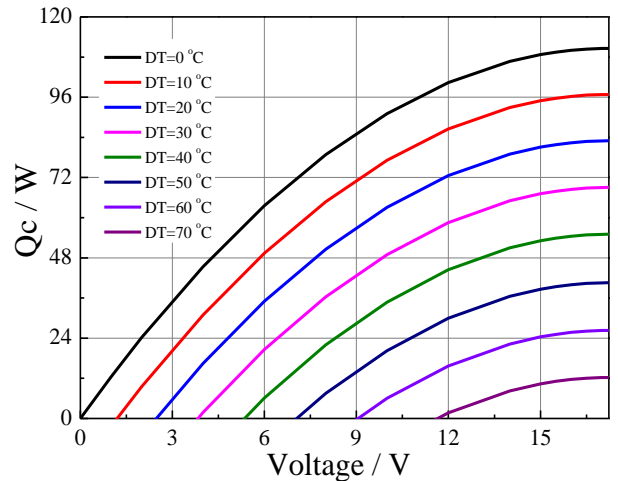
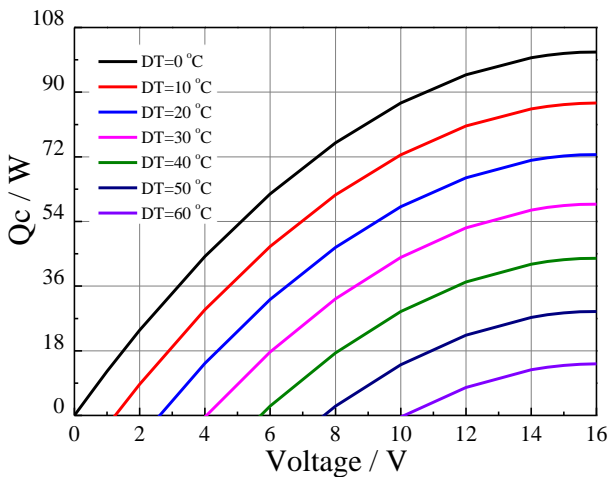
### Performance Curves at $T_h=50\text{ }^\circ\text{C}$



Standard Performance Graph  $Q_c = f(DT)$



Standard Performance Graph  $V = f(DT)$

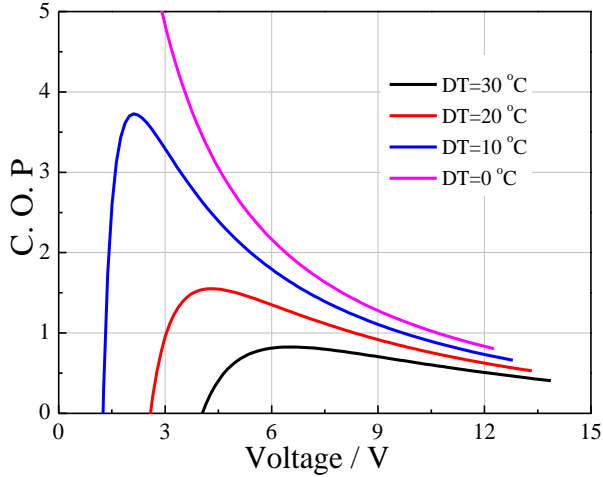


Standard Performance Graph  $Q_c = f(V)$

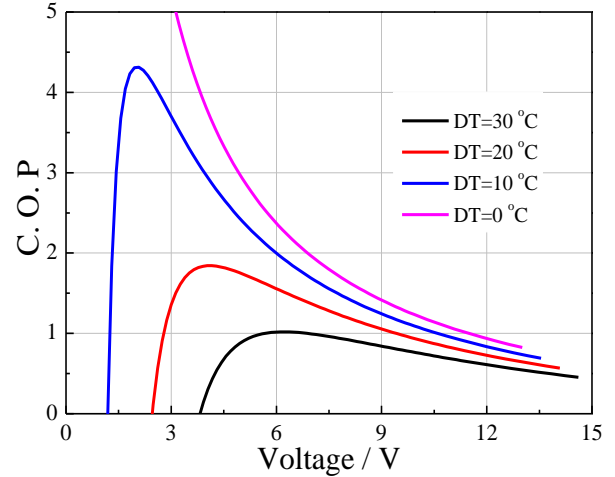
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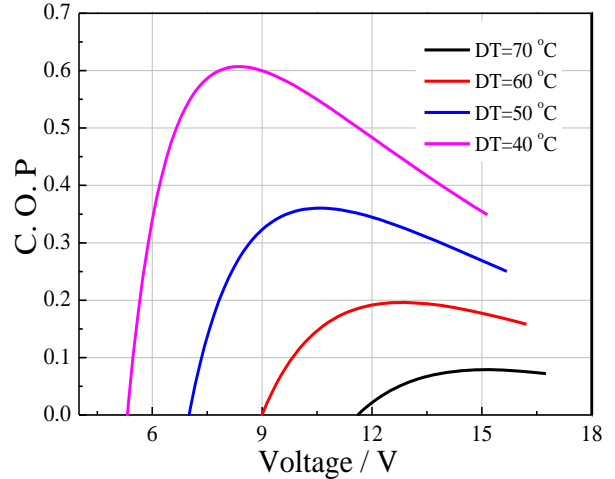
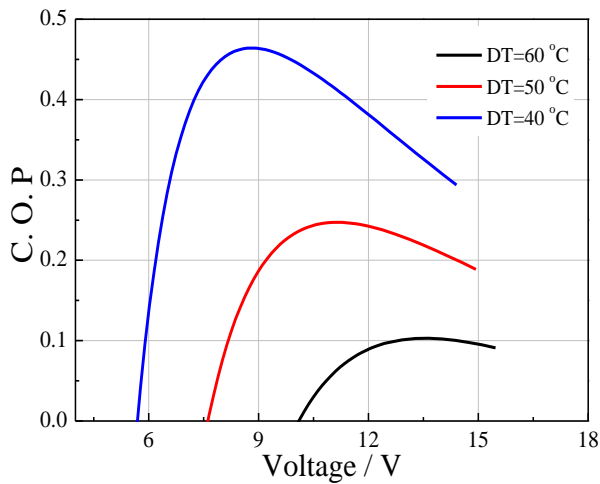
## Performance Curves at $T_h=27\text{ }^\circ\text{C}$



## Performance Curves at $T_h=50\text{ }^\circ\text{C}$



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power  $Q_c$ /Input power ( $V \times I$ ).

## Operation Cautions

- Cold side of the module applied on the object being cooled
- Hot side of the module mounted on a heat sink
- Operation below  $I_{\max}$  or  $V_{\max}$
- DC voltage only.